THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of)	Art Unit: 2829
Hongyong ZHANG et al.)	Examiner: E. Pert
Serial No. 09/695,414)	CERTIFICATE OF MAILING
Filed:	October 25, 2000)	I hereby certify that this correspondence is being deposited with The United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 2021, on
For:	METHOD FOR FORMING)	
	SEMICONDUCTOR DEVICE)	
)	

AMENDMENT

Honorable Commissioner of Patents

Washington, D.C. 20231

Sir:

In response to the Office Action dated July 23, 2002 please amend the above-identified application as follows:

IN THE CLAIMS:

Please amend claims 2, 5, 8, 11, 14 and 17 as follows:

- 2. (Amended) The method according to claim 1 wherein said metal is selected from the group consisting of Ni, Pd, Pt, Cu, Ag, Au, In, Sn, and Sb.
- 5. (Amended) The method according to claim 4 wherein said metal is selected from the group consisting of Ni, Pd, Pt, Cu, Ag, Au, In, Sn, and Sb.
- 8. (Amended) The method according to claim 7 wherein said metal is selected from the group consisting of Ni, Pd, Pt, Cu, Ag, Au, In, Sn, and Sb.
- 11. (Amended) The method according to claim 10 wherein said metal is selected from the group consisting of Ni, Pd, Pt, Cu, Ag, Au, In, Sn, and Sb.

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14. (Amended) The method according to claim 13 wherein said metal is selected from the group consisting of Ni, Pd, Pt, Cu, Ag, Au, In, Sn, and Sb.

17. (Amended) The method according to claim 16 wherein said metal is selected from the group consisting of Ni, Pd, Pt, Cu, Ag, Au, In, Sn, and Sb.